

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) An electromagnetic wave shielding material which comprises a transparent substrate, physically developed nuclei laid thereon, a layer of physically developed silver having a fine line pattern formed on said nuclei, and a metal film plated on said physically developed silver, wherein the fine line pattern has a line width of 40 μm or less, a total luminous transmittance of 50% or higher, and a surface resistance of 10 ohm/ \square or less.

2. (Currently amended) The electromagnetic wave shielding material according to Claim 1, wherein the fine line pattern has a thickness of 15 μm or less and a line width of 40 μm or less, ~~a total luminous transmittance of 50% or higher, and a surface resistance of 10 ohm/ \square or less.~~

3. (Previously presented) The electromagnetic wave shielding material according to Claim 2, wherein the total luminous transmittance is 60% or higher.

4. (Previously presented) The electromagnetic wave shielding material according to Claim 2, wherein the surface resistance is 7 ohm/ \square or less.

5. (Previously presented) The electromagnetic wave shielding material according Claim 2, wherein the thickness of the fine line pattern is 0.5 to 15 μm .

6. (Previously presented) The electromagnetic wave shielding material according to Claim 5, wherein the thickness of the fine line pattern is 2 to 12 μm .

7. (Previously presented) The electromagnetic wave shielding material according to Claim 2, wherein the line width of the fine line pattern is 1 to 40 μm .

8. (Previously presented) The electromagnetic wave shielding material according to Claim 1, wherein the plating is an electrolytic plating.

9. (Previously presented) The electromagnetic wave shielding material according to Claim 1, wherein the plating is at least one kind of plating selected from copper and nickel.

10. (Allowed) A process for preparing an electromagnetic wave shielding material which comprises exposing a light-sensitive material having a physical development nuclei layer and a silver halide emulsion layer on a transparent substrate in this order, precipitating metal silver with a pattern having an optional fine line onto the physical development nuclei layer by physical development, then,

removing a layer provided on the physical development nuclei layer, and

subjecting to plating a metal with the use of the physically developed metal silver as a catalytic nucleus to obtain an electromagnetic wave shielding material having a fine line pattern.

11. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 10, wherein the fine line pattern after the metal plating has a thickness of 15 μm or less and a line width of 40 μm or less, a total luminous transmittance of 50% or higher, and a surface resistance of 10 ohm/\square or less.

12. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 11, wherein the total luminous transmittance is 60% or higher.

13. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 11, wherein the surface resistance is 7 ohm/\square or less.

14. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 11, wherein after the metal plating the thickness of the fine line pattern is 0.5 to 15 μm .

15. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 14, wherein after the metal plating the thickness of the fine line pattern is 2 to 12 μm .

16. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 11, wherein after the metal plating the line width of the fine line pattern is 1 to 40 μm .

17. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 10, wherein the plating is an electrolytic plating.

18. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 10, wherein the plating is at least one kind of plating selected from copper and nickel.

19. (Allowed) The process for preparing an electromagnetic wave shielding material according to Claim 18, wherein an electrolytic plating is carried out by dipping a transparent substrate on which a physically developed silver has been formed in a bath containing copper sulfate and sulfuric acid as main components with a current density of 1 to 20 ampere/ dm^2 at 10 to 40°C.